

IN THE CLAIMS

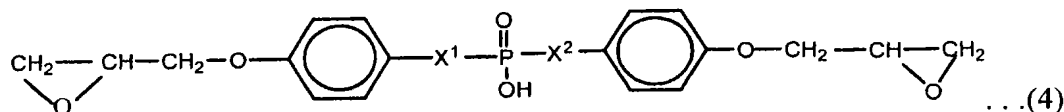
Please amend the claims as follows:

Claims 1-8 (Canceled).

Claim 9 (Currently Amended): A multilayered printed circuit board comprising:
 a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and
 a solder resist layer formed as an outermost layer,
 wherein said solder resist layer contains an elastomer component provided within at ~~least one~~ a resin selected from the group consisting of a thermoplastic resin and comprising at least a thermosetting resin, and said elastomer component is separated in micro-phase so as to form an island-in-sea structure after curing in said solder resist layer.

Claims 10-31 (Canceled)

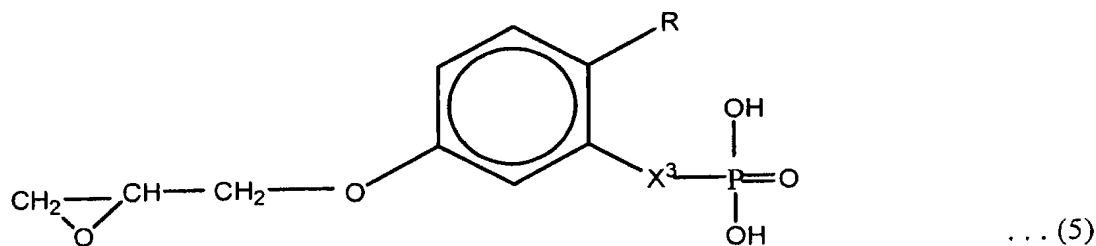
Claim 32 (Previously Presented): A multilayered printed circuit board comprising:
 a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and
 a solder resist layer formed as an outermost layer,
 wherein said solder resist layer contains a P atom-containing epoxy resin, said P atom-containing epoxy resin has bivalent phosphoric acid residue, and has epoxy groups in both terminals of the P atom-containing epoxy resin, and said epoxy resin has the following general formula (4)



wherein X¹ and , X² respectively represent O or a single bond.

Claim 33 (Canceled)

Claim 34 (Previously Presented): A multilayered printed circuit board comprising:
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and
a solder resist layer formed as an outermost layer,
wherein said solder resist layer contains a P atom-containing epoxy resin, said P atom-containing epoxy resin is an epoxy resin having a monovalent phosphoric acid residue in one terminal of the P atom-containing epoxy resin and an epoxy group in the other terminal of the P atom-containing epoxy resin, and said epoxy resin has the following general formula (5):



wherein X^3 represents O or a single bond; and R represents an alkyl of 2 to 8 carbons.

Claim 35 (Canceled).

Claim 36 (Currently Amended): A multilayered printed circuit board comprising:
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and
a solder resist layer formed as an outermost layer,
wherein said solder resist layer contains an elastomer component provided within at least one a resin selected from the group consisting of a thermoplastic resin and comprising at least a thermosetting resin, said elastomer component is at least one member selected from the group consisting of natural rubber, synthetic rubber, a thermoplastic resin and a

thermosetting resin, and said elastomer component is separated in micro-phase so as to form an island-in-sea structure after curing in said solder resist layer.

Claims 37-38 (Canceled).

Claim 39 (Previously Presented): The multilayered printed circuit board according to claim 32,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.

Claim 40 (Previously Presented): The multilayered printed circuit board according to claim 34,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.

Claim 41 (New) The multilayered printed circuit board according to claim 9, wherein the island in sea structure consists of a plurality of discrete volumes of the elastomer component distributed within a volume of the resin.

Claim 42 (New) The multilayered printed circuit board according to claim 9, wherein the at least one resin is hardened by curing.

Claim 43 (New) The multilayered printed circuit board according to claim 9, wherein the solder resist layer further comprises an inorganic filler

Claim 44 (New) The multilayered printed circuit board according to claim 9, wherein the at least one resin includes both said thermosetting resin and a thermoplastic resin.

Claim 45 (New) The multilayered printed circuit board according to claim 36, wherein the island in sea structure consists of a plurality of discrete volumes of the elastomer component distributed within a volume of the resin.

Claim 46 (New) The multilayered printed circuit board according to claim 36, wherein the at least one resin is hardened by curing.

Claim 47 (New) The multilayered printed circuit board according to claim 36, wherein the solder resist layer further comprises an inorganic filler.

Claim 48 (New) The multilayered printed circuit board according to claim 36, wherein the at least one resin includes both said thermosetting resin and a thermoplastic resin.

Claim 49 (New) The multilayered printed circuit board according to claim 9, wherein:
the island in sea structure consists of a plurality of discrete volumes of the elastomer component distributed within a volume of the resin,

the at least one resin is hardened by curing, and

the solder resist layer further comprises an inorganic filler.

Claim 50 (New) The multilayered printed circuit board according to claim 36, wherein:

the island in sea structure consists of a plurality of discrete volumes of the elastomer component distributed within a volume of the resin,

the at least one resin is hardened by curing, and

the solder resist layer further comprises an inorganic filler.